



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Z. Hu et al.

Attorney Docket No.: SEMT116058

Application No.: 10/667,802

Group Art Unit: 1764

Filed: September 22, 2003

Title: PLATINUM ALLOY USING ELECTROCHEMICAL DEPOSITION

INFORMATION DISCLOSURE STATEMENT

Seattle, Washington 98101

TO THE COMMISSIONER FOR PATENTS:

Applicants are aware of the information listed in the attached form that may be material to the prosecution of the above-identified patent application.

1. X Copies of the listed WIPO publication and other information are enclosed for the Examiner's use.
2. X Pursuant to 37 C.F.R. § 1.97(b), this Information Disclosure Statement is being filed before the mailing date of a first Office Action on the merits.

Respectfully submitted,

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I hereby certify that this correspondence is being deposited with the U.S. Postal Service in a sealed envelope as first class mail with postage thereon fully prepaid and addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the below date.

Date:

1/23/04

Shannon Hill



INFORMATION CITED BY APPLICANTS THAT MAY BE MATERIAL TO THE  
PROSECUTION OF THE SUBJECT APPLICATION

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U.S. PATENT DOCUMENTS

*Examiner Initials	Cite No.	Document No.	Kind Code	Date (mm/dd/yyyy)	Name
_____	U1	3,963,523		06/15/1976	Tanaka et al.
_____	U2	4,192,729		03/11/1980	Cancelleri et al.
_____	U3	4,243,532		01/06/1981	Tsuda et al.
_____	U4	4,285,784		08/25/1981	Flinn et al.
_____	U5	4,358,352		11/09/1982	Rhoda
_____	U6	4,427,502		01/24/1984	Abys
_____	U7	4,705,606		11/10/1987	Young et al.
_____	U8	4,750,977		06/14/1988	Marrese
_____	U9	5,232,328		08/03/1993	Owczarz et al.
_____	U10	5,310,475		05/10/1994	Kitada et al.
_____	U11	5,320,978		06/14/1994	Hsu
_____	U12	5,344,491		09/06/1994	Katou
_____	U13	5,421,991		06/06/1995	Yarita
_____	U14	5,484,518		01/16/1996	Goldberg
_____	U15	5,494,560		02/27/1996	Arimoto et al.
_____	U16	5,529,680		06/25/1996	Kitada et al.
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_____	U19	5,620,581		04/15/1997	Ang
_____	U20	5,620,583		04/15/1997	Kuhn et al.



*Examiner Initials	Cite No.	Document No.	Kind Code	Date (mm/dd/yyyy)	Name
_____	U21	5,731,678		03/24/1998	Zila et al.
_____	U22	5,789,320		08/04/1998	Andricacos et al.
_____	U23	5,972,192		10/26/1999	Dubin et al.
_____	U24	5,985,126		11/16/1999	Bleck et al.
_____	U25	6,074,544		06/13/2000	Reid et al.
_____	U26	6,077,412		06/20/2000	Ting et al.
_____	U27	6,080,291		06/27/2000	Woodruff et al.
_____	U28	6,132,587		10/17/2000	Jorne et al.
_____	U29	6,140,241		10/31/2000	Shue et al.
_____	U30	6,174,425	B1	01/16/2001	Simpson et al.

#### FOREIGN PATENT DOCUMENTS

*Examiner Initial	Cite No.	Document No.	Kind Code	Publication Date (mm/dd/yyyy)	Country	English Abstract Provided	Translation Provided
_____	F1	WO 98/02909	A1	01/22/1998	WO		

#### OTHER INFORMATION

(Including Author, Title, Date, Pertinent Pages, Etc.)

*Examiner Initial	Cite No.	
_____	O1	Lowenheim, F.A., "Electroplating," McGraw-Hill Book Company, New York, 1979, pp. 12-13, and 416-423.
_____	O2	Kotecki, D.E., et al., "(Ba, Sr)TiO <sub>3</sub> Dielectrics for Future Stacked-Capacitor DRAM," <i>International Business Machines Journal of Research Development</i> 43(3):367-382, May 1999.

Examiner

Date Considered

\*Examiner: Initial if reference considered, whether or not citation is in conformance with M.P.E.P. § 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.